ISSUE 07 – APRIL 2026

EIPC Summer Conference Lithuania

June 9 & 10, 2026

Visit: TLT PCB, Vilnius, Lithuania

"AI & Robot Integration in PCB Manufacturing"

The weather in Vilnius in Lithuania in June is glorious, with long sunny days, in a fabulous city with much to see and do. Therefore, it seems a shame to be stuck indoors all the time at an EIPC Conference, but it says much for the permanent excellence of these events that no one has ever complained. On the basis that effort = achievement, your effort in coming along to listen to our august speakers will result in a significant achievement on your part, rewarded by being in great company in a great city. It will all be too short, of course, but never to be missed.

On Day 1, Jon Custer will present the Custer Consulting Business outlook, followed by Dieter Weiss presenting the Status of the European EMS & PCB Industry, and Alison James addressing the impact of defence spending on Europe's industry. Further topics include automation in PCB manufacturing, robotics, digital twins in plating, AI-driven automation, advanced equipment for complex processes, and further insights into robotics. Advanced manufacturing will also feature thin film sputtering applications and sophisticated imaging solutions. A visit to the impressive TLT PCB plant will precede the usual Conference Dinner, totally unsuited to anyone on a diet.

Day 2 will be devoted to sophisticated chemistry, copper surface integrity for AI servers, with ESA and IMEC looking at stacked microvia reliability, and the latest HDI technology for space applications. Materials are not excluded, Ventec will be discussing their revolutionary bond film, and the University of Portsmouth ends with a paper on a truly 'green' PCB substrate offering material circularity. The topic of AI and Robotics will emerge again with a Panel Discussion led by Alpha Machines, Elinta Robotics, Elsyca and LexaTexer-Enterprise AI.

After all this, do not make a dash for the airport. Add a day on and make the most of the opportunity of being in this amazing country that has had more history than it deserves. All that you need to do now to make this a confirmed booking in your diary is to contact us.

See you in Vilnius!
EIPC Team

Conference location:

AC HOTEL VILNIUS
Vasario 16-osios 5
Vilnius, LT-01107

Tuesday June 9, 2026 Conference Day 1		
08:00-08:30	**Registration and Table top build up**	
08:30-09:00	**Welcome by EIPC President, Rico Schlüter**	
Keynote Session 1: Business Outlook and New Opportunities		**Moderator: Tarja Rapala-Virtanen, EIPC, FI**
09:00-09:30	Business Outlook: Global Electronics Industry	Jon Custer, Custer Consulting, USA
09:30-09:50	Status of the European EMS & PCB Industry	Dieter Weiss, In4ma-Data4PCB, DE
09:50-10:10	EU advocacy for strengthening Europe's Ecosystem for Defence	Alison James, GEA, BE
10:10-10:20	**Q&A**	
10:20-10.50	**Coffee break & Table top Networking**	
Session 2: Advanced PCB Manufacturing Systems: Integrating AI, Automation, and Digital Twin Technologies		**Moderator: Samuel Bismuth, CCI Eurolam, FR**
10:50-11:10	Industry 4.0 & AI: Automation in PCB manufacturing and its impact	Sultan Saidov, Alpha Machines, UK
11:10-11:30	The Role of Automation and AI in the PCB Industry: Global Trends and the Impact on Production	Aurelijus Beleckis, Elinta Robotics, LT
11:30-11:50	Use of digital twins in plating	Reshmaa Selvakumar, Elsyca, BE
11:50-12:00	**Q&A**	
Session 3: Intelligent PCB Manufacturing: Integrating AI, Robotics, and Disruptive Plating Technologies		**Moderator: Joachim Verhegge, Group ACB, BE**
12:00-12:20	AI-Driven Audit Automation in PCB Manufacturing: A Practical Assessment at Dyconex AG	Dr. G. Hoffmann, LexaTexer – Enterprise AI, DE
12:20-12:50	Future is now	Richard Kuijpers, Smart Robot Solutions, NL
12:50-13:10	The Evolution of Equipment to Improve Simplify Challenging Processes	Richard Nichols, GreenSource Engineering, PL
13:10-13:20	**Q&A**	
13:20-14:10	**Networking Lunch Hotel Restaurant**	
Session 4: Advanced PCB Manufacturing: Sputtered Thin Films and Imaging Solutions and Process control		**Moderator: Vincent Dronnet, Elvia Electronics, FR**
14:10-14:30	Impact of Sputtering Conditions on Titanium Thin-Film Resistors	Lukas Dinkelmann, Dyconex, CH
14:30-14:50	From Spectrum to System: UV Light Source Technologies for PCB Direct Imaging – Technical and Economic Trade-Offs	Dennis Pusch, Schmoll Maschinen, DE
14:50-15:10	Advanced Process Control for Inkjet Printing	Bas Le Grand, Nomenil, NL
15:10-15:20	**Q&A**	
15:20-15:30	**Coffee break & Table top Networking**	
15:30-18:00	**Departure from AC Hotel Vilnius & visit to TLT PCB**	
19:00	**Networking Dinner @ Merchants' Club "PIRKLIŲ KLUBAS"**	
22:00	**Return to AC Hotel Vilnius**	

Wednesday June 10, 2026 Conference Day 2		
Session 5: Process Solutions for High-Speed AI PCBs: Advanced Finishes & Copper Integrity		**Moderator: Thomas Michels, Ilfa GmbH, DE**
09:00-09:20	Study on Advanced Nickel-Free Final Finishes	Romina Adam, Umicore Galvanotechnik GmbH, DE
09:20-09:40	Preserving Copper Surface Integrity for High-Speed AI Server PCBs	Massimo Passerini, Wise, IT
Session 6: Pushing HDI Limits: Microvia Reliability and High-Speed PCB Technologies for Space"		**Moderator: Chris Haley, Amphenol Invotec, UK**
09:40-10:00	Stacked microvia reliability – A comparison of European manufacturers with a global benchmark	Stan Heltzel, ESA, NL
10:00-10:20	High-speed HDI technology for space applications: from design to reliability	Dr. Maarten Cauwe, IMEC, BE
Session 7: Next Generation PCB Materials: Innovations in Glass-Free and Circular Material Solutions		**Moderator: Stan Heltzel, ESA, NL**
10.20-10:40	Ventec Bond Film – VBF – The Glass Free Revolution	Volker Klafki, Ventec, DE
10.40-11:00	"Soluboard": A sustainable and functional printed circuit board for material circularity in electronics industries	Professor Abu Saifullah, University of Portsmouth, UK
11.00-11:20	**Q&A Session: 5 & 6 & 7**	
11.20-11.50	**Coffee break & Table top Networking**	
11.50-12:50	**Panel Discussion: AI and Robot integration in PCB Manufacturing** **Moderator: Rico Schlüter**	
	Panel participants: Alpha Machines, Elinta Robotics, Elsyca, LexaTexer-Enterprise AI	
12.50-12:55	**Closing remarks by EIPC President, Rico Schlüter**	
12.55-14.00	**Networking Lunch Hotel Restaurant**	

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The EIPC offers several possibilities for sponsoring the EIPC Summer Conference 2026.
Please find below the various opportunities that could be a great asset to your company's exposure.

A. GOLD:
One full colour advertisement in digital proceedings
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Logo in official sponsor list in digital proceedings
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Rate: € 2000.-

B. SILVER:
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G. PENS:
This opportunity includes pens for use by visitors available at their disposal in the registration area. Pens delivered by sponsor.
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This opportunity includes a company logo with a link to the company website in every outgoing electronic mailing regarding to this event.
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I. LOGO + REDUCED REGISTRATION FEE(S)
This opportunity includes a company logo with a link to the company website in every outgoing electronic mailing regarding to this event.
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Rate:
+ 1 delegate EIPC Member: € 900.-
+ 2 delegates EIPC Member: € 1,390.-
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+ 1 delegate NON Member: € 1,075.-
+ 2 delegates NON Member: € 1,750.-
+ 3 delegates NON Member: € 2,425.-

J. WELCOME DRINK @ NETWORKING DINNER
Visibility in all outgoing communication
Logo on conference bloc notes
Logo in official sponsor list in digital proceedings
Logo in all outgoing communication
Rate: € 1250.-
FIRST COME, FIRST SERVE

K. NETWORKING DINNER
Visibility in all outgoing communication: The "company name" networking dinner. The networking dinner is exclusively sponsored by "company name".
Cards with logo on the table during dinner
Logo on conference bloc notes
Logo in official sponsor list in digital proceedings
Logo in all outgoing communication
Rate: € 5,000.-/€ 10,000.- (depending on number of participants and menu)
FIRST COME, FIRST SERVE

If your organization is interested in exploring any of the available sponsorship opportunities, we would be pleased to discuss how we can align these options with your strategic objectives and brand visibility goals. Our team is available to provide detailed information on sponsorship packages, associated benefits and audience reach. To initiate the conversation or request additional materials, please contact us directly at **eipc@eipc.org**. We look forward to the opportunity to collaborate and develop a mutually beneficial partnership.

ISSUE 7 - APRIL 2026

ARTIFICIAL INTELLIGENCE NEWS

European AI Spending to Reach $290 Billion by 2029, Driven by Banking, Software, and Agentic AI Adoption - IDC

MILAN, April 3, 2026 - According to a new forecast from the International Data Corporation (IDC) Worldwide AI and Generative AI Spending Guide, European spending on artificial intelligence will reach $290 billion in 2029, growing at a compound annual growth rate (CAGR) of 33.7% over the 2025-2029 forecast period.

This will be driven by large spending from banking, retail and software and information services, but also from accelerating industries such as healthcare. Generative AI (GenAI) solutions are already pervasive across enterprise deployments and are expected to account for nearly 54% of the total market by the end of the period.

What is happening in the European AI and GenAI market in 2026
IDC Worldwide AI and Generative AI Spending Guide forecasts a healthy CAGR through 2029 as enterprises move from AI experimentation to strategic deployment across all major European markets, despite geopolitical tensions and supply chain disruptions.

European AI Market at a Glance
Total European AI spending by 2029: $290 billion
Forecast CAGR (2025-2029): 33.7%
GenAI share of market by end of period: ~54%
Largest technology segment: Software (58.5% of total spending in 2026)
Fastest-growing technology segment: Software (42.9% CAGR, 2025-2029)
Largest industry: Banking (12.5% of market in 2026)
Fastest-growing industry: Healthcare Provider (39.7% CAGR, 2025-2029)

“Despite geopolitical tensions and supply chain disruptions, the AI market remains dynamic and is rapidly transitioning from experimental to operational and strategic for enterprises,” said Carla La Croce, research manager, Data and Analytics, IDC. “Organisations are no longer treating AI as a standalone tool - they are repositioning it as a strategic asset to transform

their business models. The emergence of agentic AI tools has made this transformation more urgent and more profound than many anticipated".

Market Dynamics & Outlook

Why is European AI spending surging despite macro headwinds

AI platforms and GenAI solutions deliver measurable returns in cost efficiency, customer experience, and risk management. As a result, enterprises are accelerating budget reallocation toward AI, shifting from experimental pilots to mission-critical, multi-agent deployments. Software is leading this charge, growing at a 42.9% CAGR with AI Platforms at 52.5%, driven by the explosion of agentic components across industries.

What is IDC's outlook for the European AI market

European AI spending will maintain strong double-digit growth through 2029, sustained by AI Platform expansion, cloud-native development, and industry-specific AI embedding into enterprise strategies. Agentic AI is the key growth catalyst. Risks include regulatory fragmentation from the EU AI Act, persistent AI talent shortages, and cloud cost optimisation pressures - all of which will create incremental demand for AI governance and assurance services.

Industry Trends: Where AI Investment Is Concentrated

Banking leads European AI spending (12% of the market), with use cases such as fraud analysis, threat intelligence, contact centers, and customer self-service, with institutions shifting from pilots to mission-critical multi-agent automation and increased focus on FinOps, sovereign cloud, and AI governance.

Software and information services follow, with most spending on AI infrastructure provisioning to support agentic workloads via PaaS and IaaS. Retail ranks third, investing in digital commerce, AI-enabled customer service, planning, personalization, pricing, and supply-chain optimization.

Fast-Growing Industries

Healthcare Provider: Fastest-growing industry at 39.7% CAGR (2025-2029) across all five major markets. Primary use case: Clinical Workflow and Resources Optimization.

Media & Entertainment: 37.3% CAGR, driven by GenAI for content creation, video production, and audience personalization.

Also, above-average growth: Professional and Personal Services, Utilities, and Life Sciences.

FAQs

Why is European AI spending growing faster than overall IT spending?

AI platforms and GenAI solutions deliver measurable returns in cost efficiency, customer experience, and risk management, driving enterprises to prioritize AI investment over traditional IT expenditure. The shift from experimental pilots to strategic deployment is accelerating budget reallocation across all major European markets.

Which industries offer the most opportunity for AI vendors

Banking is the single largest industry in four of the five major markets. Healthcare Provider is the fastest growing across all five. Media and Entertainment, Insurance, and Professional

Services also offer above-average growth. Fraud prevention, threat intelligence, customer service automation, and AI infrastructure provisioning represent the broadest cross-market opportunities.

What risks could impact the market

Regulatory fragmentation across EU member states, persistent AI talent shortages, and cloud cost optimization pressures are the primary constraints. The EU AI Act will continue to shape investment patterns, with compliance spending creating incremental demand for AI governance services - particularly in banking, insurance, and healthcare.

About IDC

International Data Corporation (IDC) is the premier global provider of trusted technology intelligence, advisory services, and events. With more than 1,000 analysts worldwide, IDC offers global, regional, and local expertise on technology, IT benchmarking and sourcing, and industry opportunities and trends in over 100 countries. IDC's analysis and insights help IT professionals, business executives, and the investment community to make fact-based technology decisions and to achieve their key business objectives. To learn more about IDC, please visit www.idc.com. Follow IDC on X at @IDC and LinkedIn. Subscribe to the IDC Blog for industry news and insights.

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NEWS FROM CANADA

Firan Technology Group Corporation ("FTG") Announces First Quarter 2026 Financial Results

Firan Technology Group Corporation (TSX: FTG) (OTCQX: FTGFF) today announced financial results for first quarter of 2026.

First Quarter Financial Highlights:

- Bookings: $60.0 million, marking a 17% increase over Q1 2025 and a book-to-bill ratio of 1.27:1
- Backlog: The quarter-end backlog stood at $157.9 million, an 11% rise from the previous year end.
- Revenue: $47.3 million, a 10.3% increase over Q1 2025.
- Adjusted EBITDA: $7.3 million, down from $8.4 million in Q1 2025.
- Adjusted Net Earnings: $3.5 million, up from $3.3 million in Q1 2025.
- Free Cash Flow: Generated free cash flow of $4.9M in Q1 2026.
- Net Debt: Maintained a strong balance sheet with net debt of $4.0 million, or 0.1X trailing 12 months EBITDA, including $9.9 million of government loans.

Business Highlights:
In Q1 2026, the Corporation grew organically. FTG is strategically investing its capital in ways that will drive increased shareholder returns for the future in both the near term and long term. The company's achievements in Q1 2026 demonstrate this commitment, laying a strong foundation for future growth.

Growing FTG's defence business: FTG Circuits qualified for two significant classified defence programs in 2025. Initial orders have been placed for these programs and deliveries are expected to take place in Q3 2026 and beyond.

Creating value from FTG Aerospace Calgary: FTG Aerospace Calgary, formerly FLYHT, achieved record profitability in Q1 2026. The newest site of FTG continues to benefit from efforts to obtain certifications, sell its existing product portfolio and the restarting of licensing revenues related to their Satcom radio for Airbus.

Diversifying and reducing exposure to U.S. tariff risks: In Q1 2026, deliveries to China's C919 program

continued. In addition, deliveries to the new De Havilland Canadair 515 (DHC-515) aerial firefighting aircraft started to ramp up. More deliveries on both programs are expected for the remainder of 2026.

Participation in space programs: FTG is proud to support the Artemis mission by supplying Switch Interface Panels (SIPs) to the Orion spacecraft. Although space represents a small portion of FTG's business, space is a growing sector and FTG has activities with other customers in the sector.

About Firan Technology Group Corporation:
FTG is an aerospace and defence electronics product and subsystem supplier to customers around the globe. FTG has two operating units:
FTG Circuits is a manufacturer of high technology, high reliability printed circuit boards. Our customers are leaders in the aviation and defence industries. FTG Circuits has operations in Toronto, Ontario, Chatsworth, California, Fredericksburg, Virginia, Minnetonka, Minnesota, Haverhill, Massachusetts and a joint venture in Tianjin, China.

FTG Aerospace designs, certifies, manufactures and provides in-service support for illuminated cockpit products, electronic assemblies and avionics products for original equipment manufacturers and operators of aerospace and defence equipment. FTG Aerospace has operations in Toronto, Ontario, Calgary, Alberta, Chatsworth, California and Tianjin, China.
The Corporation's shares are traded on the Toronto Stock Exchange under the symbol FTG, and on the OTCQX Exchange under the symbol FTGFF.

Bradley C. Bourne, President and CEO
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Head Office: 250 Finchdene Square, Toronto, Ontario, M1X 1A5
Additional information can be found at the Corporation's website www.ftgcorp.com.

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NEWS FROM EUROPE

Europe at a turning point for PCB base materials

April 08, 2026
Ewelina Bednarz
Evertiq

As performance requirements for printed circuit boards continue to rise - driven by high-speed digital as well as RF and microwave applications - the development and selection of base materials is becoming a balancing act between electrical performance, regulatory compliance and supply chain resilience. What used to be a largely engineering-driven decision is now increasingly influenced by external constraints that are harder to control and even harder to predict.

In Europe, this shift is taking place against a backdrop of a steadily shrinking industrial base. The old continent has been reduced to a single base material supplier - Isola GmbH - and one copper foil producer, CircuitFoil, while already losing its woven electronic glass manufacturing capabilities - a development that places increasing pressure on the remaining parts of the ecosystem.

“We are actually at a critical point,” says Alexander Ippich, Technical Director, Signal Integrity & Advanced Technology and Product Manager RF/Microwave in Isola GmbH, in an interview with Evertiq. “We still have a single European base material supplier as well as a copper foil supplier. But Europe has already lost all woven electronic glass suppliers.”
This erosion did not happen overnight. For years, discussions around local sourcing and European supply chains remained largely theoretical - acknowledged as important but rarely reflected in actual procurement decisions.
That dynamic now appears to be shifting.

“I actually see a real shift in OEM customers selecting material suppliers from Europe,” Ippich tells Evertiq. “For many years, this was always mentioned as a ‘good thing to do’, but most of the time there was no follow-through.” What is changing is not only where materials are sourced, but also why. In sectors such as space, aerospace and defence, supply

security and long-term reliability are beginning to outweigh purely cost-driven considerations.

“Now, particularly in space, aerospace and defense applications, the shift is happening,” he explains. “This is for materials with higher electrical performance for HSD and RF/MW applications, but also for the FR4 area. Pricing is mentioned as a lesser concern now.”

At the same time, the regulatory environment in Europe is adding another layer of complexity - one that directly affects how materials are developed and qualified. Frameworks such as REACH and the continuously evolving SVHC list do not only impose constraints but also introduce a degree of uncertainty into long development cycles.

“I do feel that those regulations make things more complicated,” Ippich says. “We may be in compliance with SVHC at a certain time, but with the next revision we may again see components being flagged, as there are new additions all the time.”

This creates a structural mismatch between regulatory timelines and industrial processes, where developing and qualifying new materials can take quite long.

“Developing a new base material formulation and the time needed for UL approval is quite lengthy, and it is impossible to react to new additions to the SVHC quickly,” he adds.
Within this context, the debate around PFAS becomes part of a broader transition, rather than an isolated regulatory issue. The search for alternatives is no longer only about compliance, but also about maintaining performance while adapting to a changing materials landscape.

“As for PFAS, we are in excellent shape,” Ippich notes. “We do have products that can deliver PTFE performance, but do not include PFAS components.”
Yet even as innovation continues, the question remains whether Europe can sustain - or rebuild - its material ecosystem.
“There is still know-how, so this could be brought back to life, but we cannot afford to wait too long and potentially lose more critical components,” Ippich explains to Evertiq. “It is important that the European Union and the OEMs do use the local supply chain to keep it active.”

The same tension is visible further down the value chain. Europe still maintains a few highly capable PCB fabrication facilities, but their position depends increasingly on sourcing decisions.
“For PCB fabs, we still do have quite a number of very capable ones, but they also need to be supported and not always replaced by a lower-cost Asian supplier,” he adds.
Alexander Ippich will speak at Evertiq Expo Zurich on 23 April, addressing how performance requirements, regulatory constraints and supply chain realities interact in the development and selection of PCB base materials.

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NEWS FROM THE ICT

ICT SPRING EVENING SEMINAR

Our ICT Spring Evening Seminar & AGM is just a week away now, on the 14th of April at The Manor Hotel in Meriden.

In addition to the speakers announced last week, we're very pleased to announce our final speaker for the evening seminar part of the event. We have the pleasure in welcoming **Richard Nichols** from **GreenSource Engineering** to talk to us about whether invention is still alive in the European PCB industry.

With Richard and the **Plasma Innovations** team speaking at the evening seminar and the new **EIPC President**, **Rico Schluter**, talking collaboration within Europe as part of the AGM open forum, can you afford to miss it?

We welcome members and potential new members for the AGM and evening seminar; we need to hear from you about what the ICT can do to bring value to the PCB industry in the UK. The Institute is here for its members, so come along and have your say about what it is you need from us.

Running order for the day will be:

ICT Council Meeting (invite only)	*12pm – 2.15pm*
PCB Fabricator Group Meeting (invite only)	*2.30pm - 5pm*
Pre-AGM Drinks and Nibbles	**6pm**
AGM / Evening Seminar	**6.30pm**
Buffet	**8.30pm**

We hope to see you on the 14th of April and hear what ideas you have for the future of the ICT. **Please let me know if you will be joining us** or if you have any questions about the evening.

Emma Hudson (FInstCT),Technical Director, Institute of Circuit Technology, Tel: +44 7551 931182 www.instct.org

ISSUE 7 – APRIL 2026

NEWS FROM THE UK

Provisional Programme Announced

Electronics for Extreme Environments Conference 2026
"electronics that must endure"

Two Day Conference on 30th June and 1st July 2026 at Churchill College Cambridge

The Electronics for Extreme Environments 2026 Conference focuses on Electronics That Must Endure. This in-person Conference combines invited Keynotes, Presentations and Posters from leading Industrial Companies, Academics and Research Institutions developing sensors, semiconductors, components, energy sources, packaging and assemblies that must perform reliably under extreme conditions, including high and low temperatures, high field strengths, severe mechanical and environmental conditions and ultra-long-life electronics. This Conference follows on from and extends the High Temperature Electronics Network (HITEN).

The Electronics for Extreme Environments 2026 Conference will provide examples of the implementation of electronics packaging in challenging applications, where electronics and sensors must improve the control of energy intensive processes, ensure safety in hostile

industrial environments, work reliably in extreme natural conditions and provide security in critical applications.

Keynote Speakers
Iain Mauchline – UKRI, United Kingdom – Support for Semiconductor and Advanced Packaging Development for the UK Electronics Industry
Matthew Somans – ESA International, The Netherlands – Detectors Developed to Operate in Space at Cryogenic Temperatures
Nick Sykes – UKAEA, United Kingdom – Need for Radiation Tolerant, High Temperature and/or High Magnetic Resistant Electronics in Fusion
Andrew Wright – Sandia National Laboratories, USA – 300°C Geothermal Embedded Electronic Systems

Electronics for Extreme Environments Conference Programme Summary

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<tr><th colspan="2">Electronics for Extreme Environments Conference Topics</th></tr>
<tr><th>Session 1: High Temperature</th><th>Session 2: Applications</th></tr>
<tr><td>Aircraft Power Systems
SiC JFET Circuit Design
Ku-Band Substrates
Thermally Hardened Electronics for Power and RF
MEMS for Ultra-Low Power Edge AI
NEM Switches</td><td>Electronics Design for Outer Space
High Survivability Electronics in Defence and Security
Cryogenic Power Electronics for Hydrogen Powered Electric Aircraft
Heat Resistant Solid-State Batteries</td></tr>
<tr><th>Session 3: High Field Strengths</th><th>Session 4: Severe Environmental Conditions</th></tr>
<tr><td>Total Dose Radiation Effects in Fusion
Performance of Wide Bandgap Electronics and Photonics in Gamma Irradiation
Stability of GaN HEMTS in Radiation
Electronics for Nuclear Camera Systems
Memory Testing
Active and Passive Filtering in Electro-magnetic Environments</td><td>Silicon Capacitors
Novel Condensation Test Method
High Voltage Dielectric Behaviour at Low Pressure
Technology Maturity Assessment for Challenging Environments</td></tr>
</table>

Current Exhibitors

Gen3 - Specialist British Manufacturer and Distributor of Test and Measurement Equipment

Inseto UK - Premier Technical Distributor of Equipment and related Materials to the Semiconductor, Microelectronics and Advanced Technology Sectors, supplemented with the supply of a range of adhesives to electronics, automotive and industrial manufacturing industries

IPP Group/Cupio Services - Innovative Inspection, Production and Test Solutions

Maxell Europe - A New Generation of Solid-State Battery that Changes the Concept of Power Usage

Micro-Hybrid GmbH - Electronics Modules and Solutions, Sensors – IR Emitters – IR Detectors -

There are further Sponsorship and Exhibiting opportunities at the Electronics for Extreme Environments Conference, please visit the **Conference Event Page** or contact the IMAPS-UK Office (**office@imaps.org.uk**) for more information.

Electronics for Extreme Environments Conference 2026 - Click Here

For Any other details or information Please contact:
IMAPS-UK Secretariat
125 High Street Chesterton, Cambridge, UK
Tel: +44 0131 2029004
e-mail: **Office@imaps.org.uk**

News from
WECC members

WECC
World Electronic Circuits Council

Issue 7 – April 2026

NEWS FROM THE TPCA

PCB bottlenecks, freight costs push electronics prices higher

Apr 7, 2026
Jerry Yang, Taipei
Digitimes

The global electronics supply chain is facing a cost shock not seen in years. War in Iran, surging AI demand, and tight capacity are simultaneously driving up prices across raw materials, key components, and logistics.

Component shortages deepen, price hikes broaden
According to Nikkei Asia, cost pressures have spread well beyond memory and CPUs. STMicroelectronics has informed customers of price increases from April, citing higher energy, transport, and capacity-related costs.

Japan-based Murata Manufacturing has raised prices for components such as inductors, reflecting higher input costs including silver. China-based Kingboard Laminates Holdings, the world's largest copper-clad laminate supplier, has lifted prices three times in three months following a surge in petrochemical costs linked to the Iran conflict.

Rising costs are now feeding into lead times. A key bottleneck has emerged in printed circuit boards (PCBs), a core component in electronics manufacturing. Natarajan Ramachandran, director of product marketing in Broadcom's Physical Layer Products division, stated that lead times have increased from around six weeks to as long as six months.

Ramachandran noted that the tightest supply is in PCBs used for transceivers in AI networking equipment. These once-standard components are now a key constraint, delaying broader supply chain delivery.

Freight costs rise, pressure spreads
Middle East tensions are also pushing up oil and shipping costs. UPS has raised rates several times since March, while key metals such as copper and aluminium remain near multi-year highs.
Industry executives expect broad-based price increases in 2026. If the conflict continues, the impact could extend beyond electronics to everyday goods such as plastic packaging. Even with a ceasefire, supply chain disruptions are unlikely to ease in the near term.

AI demand fuels revenue growth across the PCB sector in March

2026/04/08

Taiwan Printed Circuit Association

Strong AI demand has driven the operations of the printed circuit board (PCB) sector. Zhen Ding's revenue in March and the first quarter both hit record highs for the same period, with server and IC substrate businesses experiencing rapid growth. Giant Elastos benefited from stable growth in demand for AI servers and high-end substrates, achieving record revenue in March. Teng Hui benefited from the fruitful results of its long-term investment in high-margin aerospace polyimide (PI) materials.

Global PCB giant Zhen Ding today announced consolidated revenue of NT$15.443 billion in March, a 31.76% increase month-over-month and a 7.18% increase year-over-year, setting a new record for the same period. First-quarter revenue reached NT$40.728 billion, a 1.61% increase year-over-year, also setting a new record for the same period.

Zhen Ding stated that March revenue continued to benefit from strong demand for high-end AI-related products, with server and optical communication revenue increasing by over 190% year-over-year, setting a new monthly record. IC substrates saw accelerated growth driven by high-end applications, increasing by over 70% year-over-year, also setting a new monthly record. Overall, the first quarter of this year clearly saw high-end AI applications become the core driver of growth, with server, optical communication, and IC substrate businesses accounting for nearly 20% of total revenue, and the product portfolio continuing to move towards higher-end products.

Zhen Ding pointed out that starting from the second quarter, as customers' next-generation platforms gradually enter mass production, the momentum of server and optical communication businesses will increase quarter by quarter; IC substrates will benefit from strong demand related to AI computing power and grow quarter by quarter. Zhen Ding has already reached long-term cooperation agreements with several key customers regarding future-generation high-end AI product needs and will further increase its capital expenditure to over NT$80 billion.

Asia Electronics' consolidated revenue in March was NT$117 million, roughly the same as the same period last year; cumulative consolidated revenue for the first quarter was NT$314 million, a year-on-year decrease of 6.23%.

Asia Electronics stated that after the Lunar New Year, it adjusted its capacity allocation, transferring large-scale production of mature narrow-width processes to its Dongtai plant, while maintaining high-tech products at its Kunshan plant; in addition, in recent years, price competition in the flexible printed circuit board industry in mainland China has become increasingly fierce, and it will prudently adjust its order-taking strategy.

Asia Electronics stated that it will continue to expand its presence in high-end application fields this year, covering markets such as semiconductors, automotive energy storage, servers, and aerospace and defence, and actively promote the sampling and certification process for high-end new products.

Giant Rubber Industries reported a record high consolidated revenue of NT$148 million in March, representing a 68% increase compared to February and a 32% increase compared to the same period last year; cumulative consolidated revenue for the first quarter reached NT$364 million, a 21% year-on-year increase.

Giant Rubber stated that the revenue growth in March was mainly driven by the simultaneous increase in shipments from key customers in Taiwan and mainland China, boosting overall revenue performance. Specifically, the Taiwan market continued to benefit from stable growth in demand for AI servers and high-end substrates, resulting in strong shipments of high-end materials; the mainland China market contributed across the board, from low-end to high-end products, significantly increasing overall shipments.

Copper foil substrate manufacturer Teng Hui reported revenue of NT$481 million in March, a 35% increase month-on-month and a 33% increase year-on-year; cumulative revenue for the first quarter reached NT$1.24 billion, a 22% increase year-on-year and a 12% increase quarter-on-quarter. TengHui achieved double-digit growth in both monthly and cumulative figures this year, returning to a significant growth trajectory and reaching a new high in nearly four years.

TengHui stated that the revenue surge was primarily due to the fruitful results of its long-term investment in high-margin aerospace polyimide (PI) materials. Orders for this product reached a record high in January and broke that record again in March, with a monthly increase of 52%. Cumulative revenue for the first quarter more than doubled year-on-year and grew by 50% compared to the fourth quarter of last year.
Looking ahead, TengHui stated that in addition to benefiting from international tensions and increased defence budgets by various countries, it has also gained recognition from semiconductor testing equipment manufacturers. Mass production of new materials continues to increase, with applications such as rocket launch motherboards and sideboards for low-Earth orbit satellites, AR, VR, robotics, and manned flight vehicles receiving end-user certification and initial orders beginning to ramp up.

Furthermore, with the continued rise in prices of raw materials such as fiberglass cloth and resin, TengHui stated that it has successfully passed on the price increases to its customers and expects the price hike effect to gradually take hold and contribute to revenue.
(News source: United Daily News)

International Diary

2026

HDP Spring Member Meeting
June 3-4
Bangkok, Thailand

EIPC Summer Conference Vilnius
9 & 10 June
Vilnius, Lithuania
Visit TLT PCB

JPCA
10-12 June
Tokyo, Japan

FED Austrian Electronics Day
18 June
Salzburg, Austria

IPCA
29-31 July
New Delhi, India

KPCA
9-11 September
Incheon, Korea

EIPC @ FED Conference
23 & 24 September
Bamberg, Germany

EIPC @ EFX 2026
6-8 October
Stuttgart, Germany

TPCA
20-22 October
Taipei, Taiwan

EIPC @ Electronica 2026
10-13 November
Munchen, Germany

FED Austrian Electronics Day
26 November
Dornbirn, Austria

HKPCA
2-4 December
Shenzhen, Hong Kong